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Dated: April 14, 2005

Signature: 

Linda J. Werk

Ref.: 7452-103/10312955
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chih-Liang CHU, et al.

Confirmation No.: 3449

Application No.: 10/683,814

Group Art Unit: 2826

Filed: October 9, 2003

Examiner: ANDUJAR, Leonardo

For: SEMICONDUCTOR PACKAGE
SUBSTRATE HAVING BONDING PADS
WITH PLATED LAYER THEREON AND
PROCESS OF MANUFACTURING THE
SAME

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the requirement for restriction in the Office Action dated March 23, 2005, Applicant hereby elects with traverse Group I, claims 15-17, drawn to a semiconductor device.

REMARKS

Applicant elects Group I, claims 15-17, with traverse. An early action on the merits is awaited.